BAS70W / BAS70W-04 / BAS70W-05 / BAS70W-06

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BAS70W / BAS70W-04 / BAS70W-05 / BAS70W-06

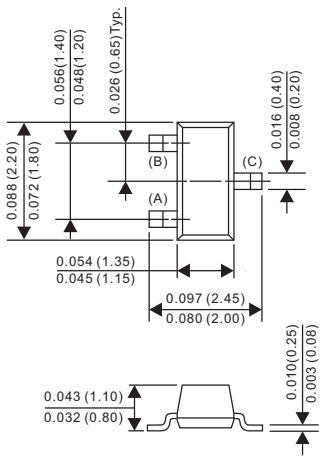
70mA Surface Mount
Small Signal Schottky Diodes 70V

Features

- Low current rectification and high speed switching.
- Tiny surface mount type.
- Up to 200mA current capability.
- Low forward voltage drop (V_F = 1.00V typ. @15mA)
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts for green partner, exceeds environmental standards of MIL-STD-19500 /228
- High speed (trr < 5 ns)
- Suffix "-H" indicates Halogen-free part, ex.BAS70W-H.

Package outline

SOT-323



Dimensions in inches and (millimeters)

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOT-323
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any
- Weight : Approximated 0.006 gram

Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Repetitive peak reverse voltage		V_{RRM}			70	V
Reverse voltage		V_R			70	V
Power dissipation		P_D			200	mW
Non-Repetitive Peak Forward Surge Current	tp<8.3ms	I_{FSM}			100	mA
Forward current		I_F			70	mA
Junction temperature		T_J	-55		+125	°C
Storage temperature		T_{STG}	-55		+150	°C
Forward voltage	I_F = 1 mA	V_F			0.41	V
	I_F = 15 mA	V_F			1.00	V
Reverse current	V_R = 50 V	I_R			0.1	uA
Diode capacitance	V_R = 0 V, f = 1MHz	C_D			2.0	pF
Reverse recovery time	I_F=I_R =10mA, $I_{R(Rec)}$=1.0mA	trr			5	ns
Thermal Resistance	Junction to Ambient Air	$R_{\theta JA}$			500	°C/W

Rating and characteristic curves for each diode (BAS70W / BAS70W-04 / BAS70W-05 / BAS70W-06)

FIG.1 Forward Characteristics

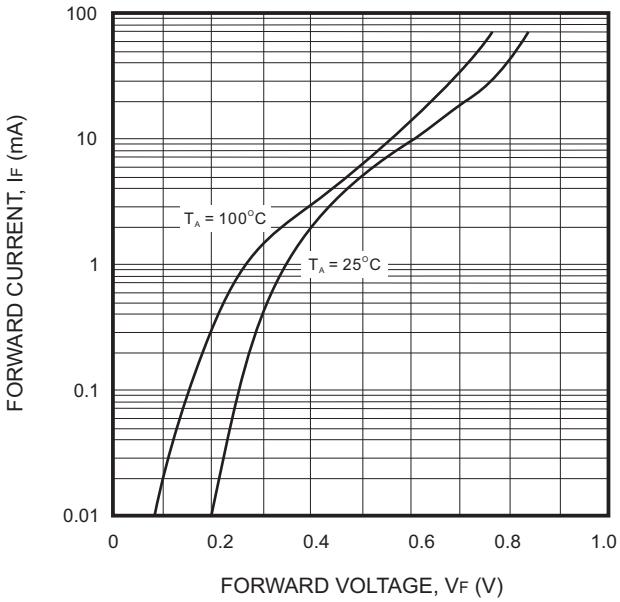


FIG.2 Reverse Characteristics

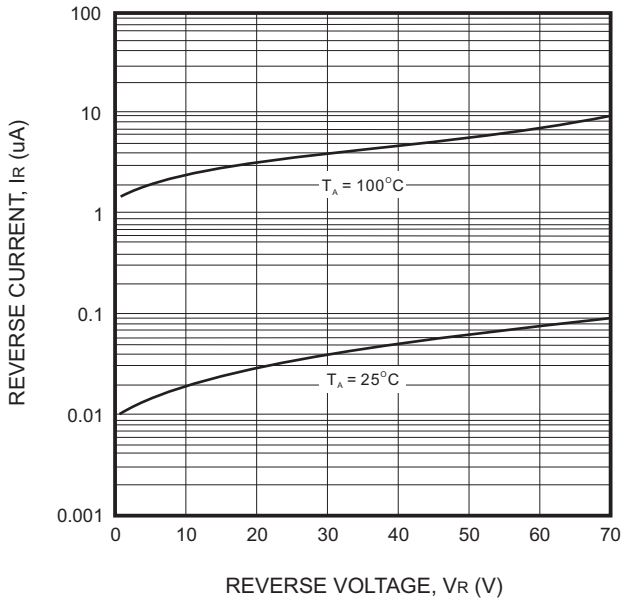


FIG.3 Power Derating Curve

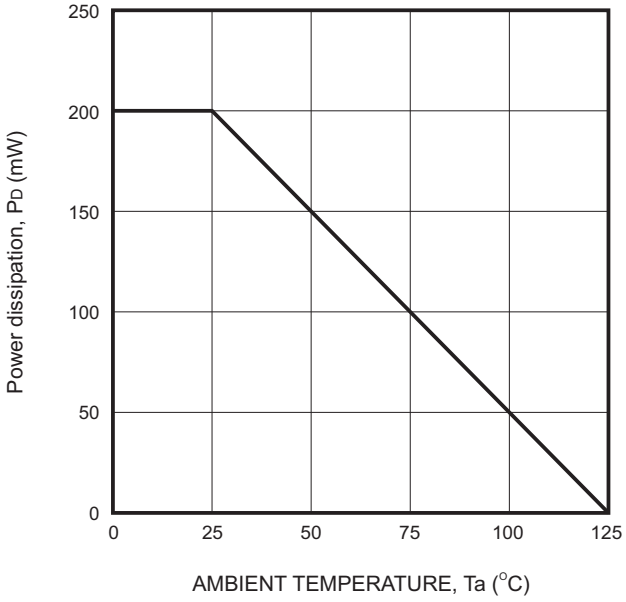
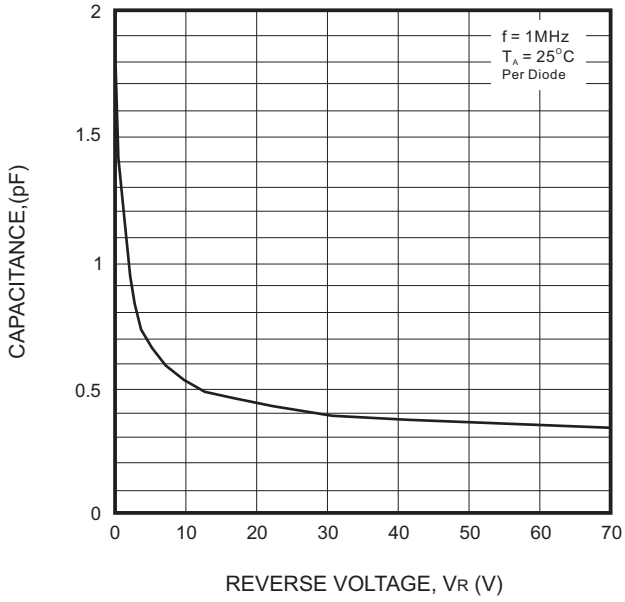


FIG.4 Capacitance Characteristics



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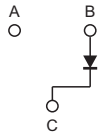
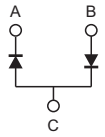
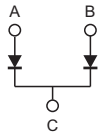
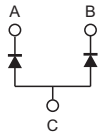
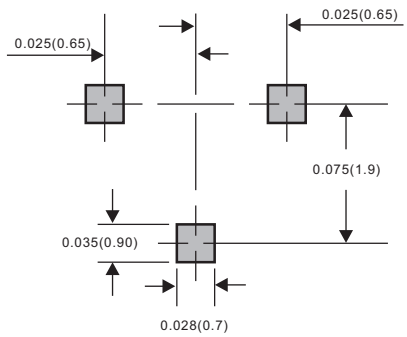
Pinning information

Type number	Marking code	Symbol
BAS70W	K73	
BAS70W-04	K74	
BAS70W-05	K75	
BAS70W-06	K76	

Suggested solder pad layout

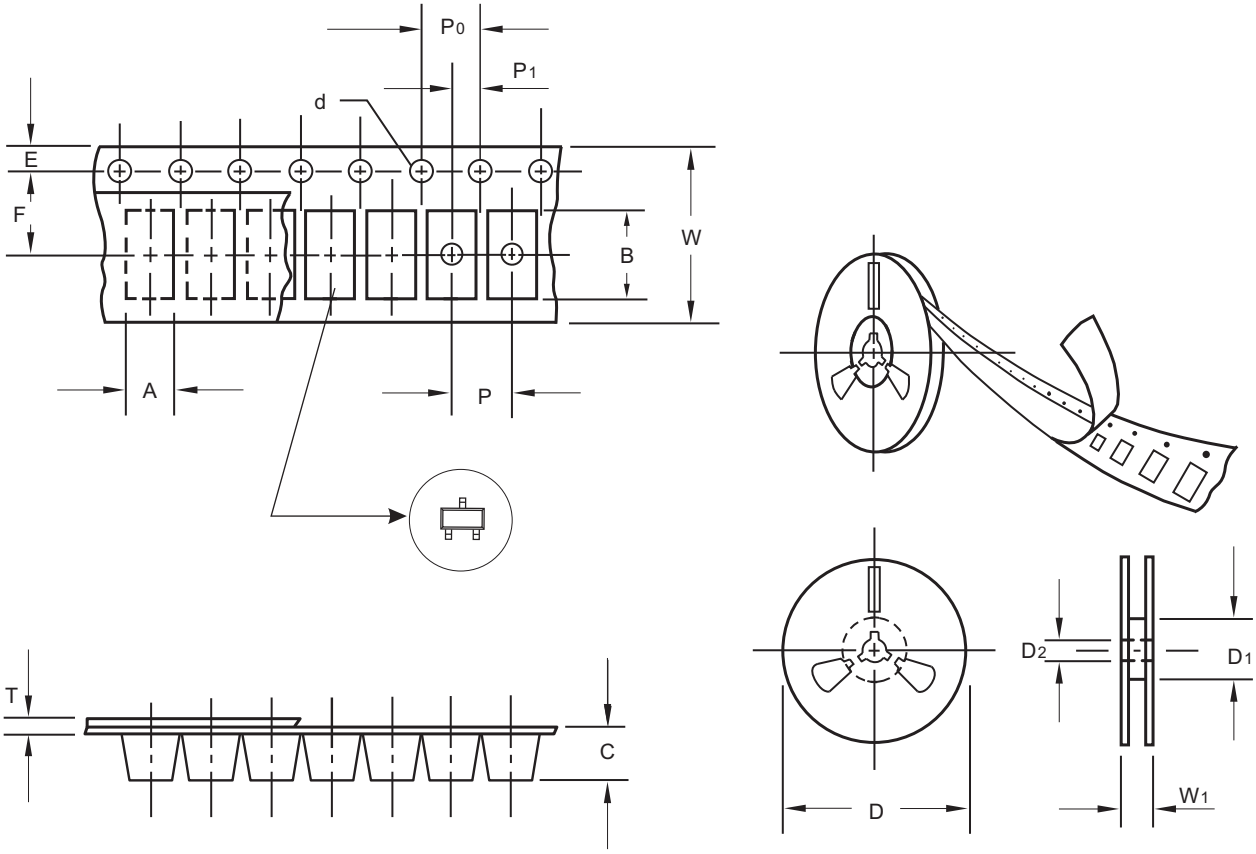
SOT-323



Dimensions in inches and (millimeters)

BAS70W / BAS70W-04 / BAS70W-05 / BAS70W-06

Packing information



unit:mm

Item	Symbol	Tolerance	SOT-323
Carrier width	A	0.1	2.36
Carrier length	B	0.1	2.40
Carrier depth	C	0.1	1.20
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D_1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D_1	min	62.00
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W_1	1.0	11.40

Note:Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

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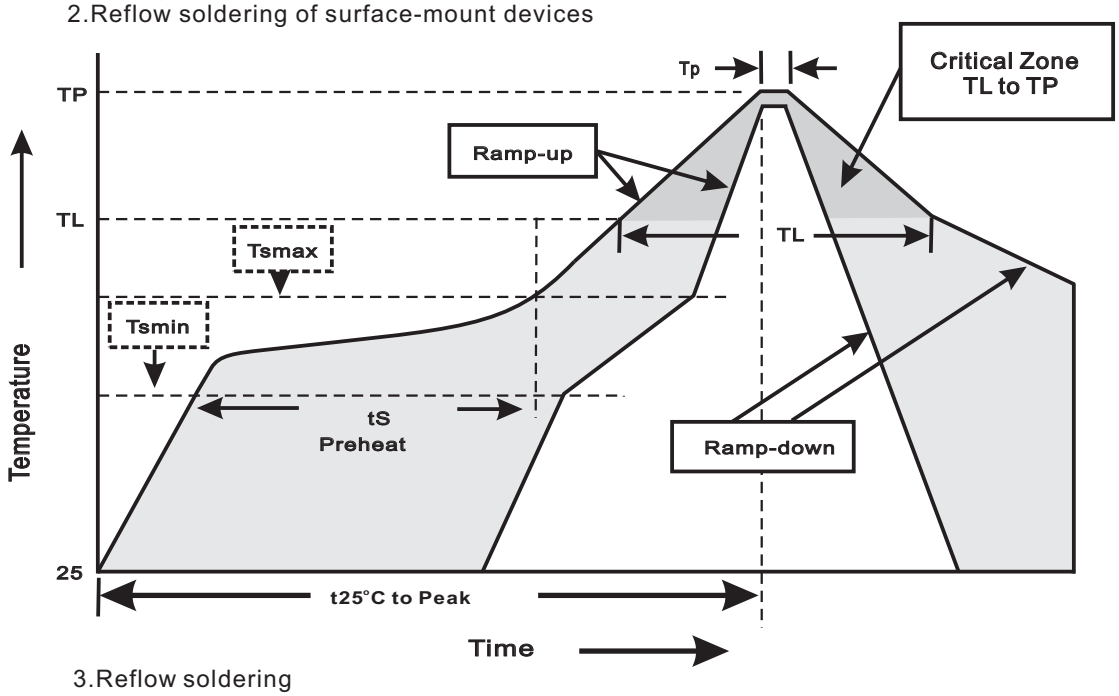
Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOT-323	7"	3,000	4.0	30,000	183*183*123	178	382*262*387	240,000	9.5

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(t_s)	 150°C 200°C 60~120sec
Tsmax to T_L -Ramp-upRate	 <3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	 217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec. immerse body into solder 1/16"±1/32"	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	V_R=80% rate at T_J=125°C for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at T_A=25°C for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	T_A = 25°C, I_F = I_O On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	15P_{SIG} at T_A=121°C for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
9. Forward Surge	Non-Repetitive Forward Current tp<1s	MIL-STD-750D METHOD-4066-2
10. Humidity	at T_A=85°C, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
11. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031